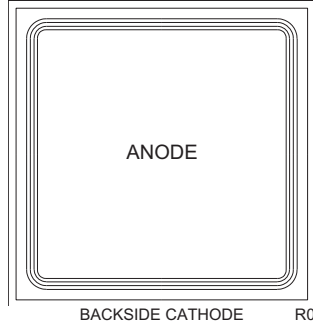


CPD85V-CMP SH1-4L

Schottky Rectifier Die

1.0 Amp, 40 Volt

The CPD85V-CMP SH1-4L is an ultra low V_F silicon Schottky rectifier designed for applications where operational efficiency is a prime requirement.



MECHANICAL SPECIFICATIONS:

Die Size	39.4 x 39.4 MILS
Die Thickness	7.1 MILS
Anode Bonding Pad Size	35 x 35 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 9,000Å
Scribe Alley Width	1.97 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	10,900

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

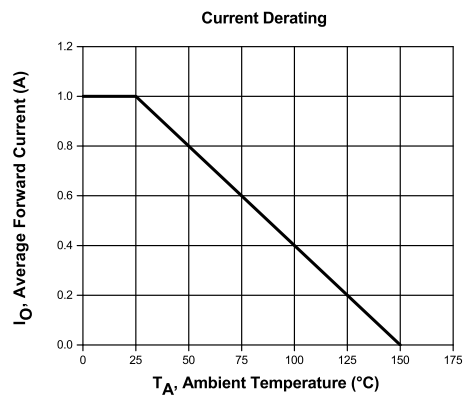
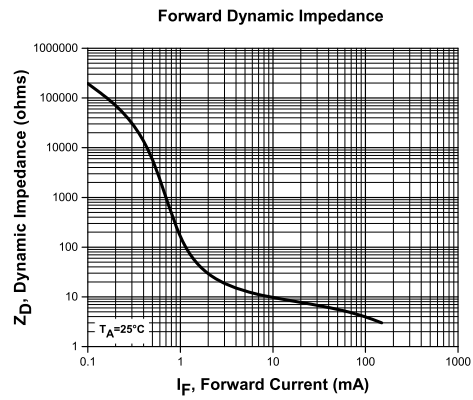
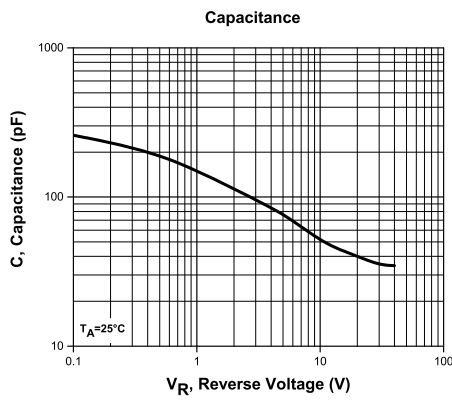
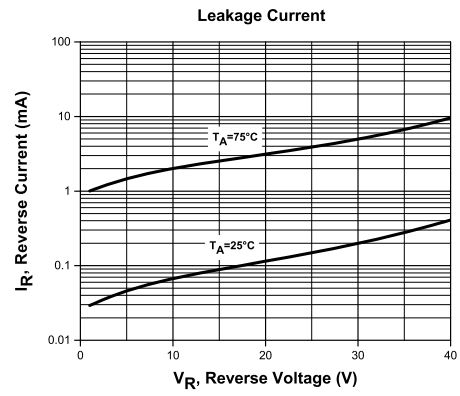
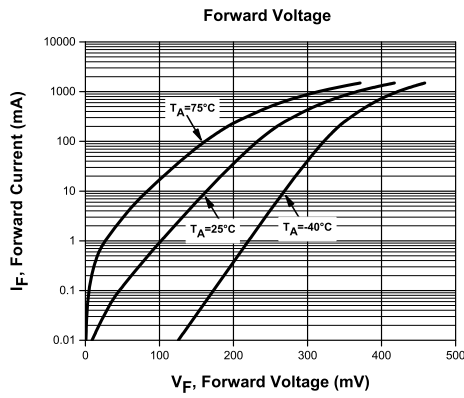
	SYMBOL		UNITS
Continuous Reverse Voltage	V_R	40	V
Average Forward Current	I_O	1.0	A
Peak Forward Surge Current, $t_p=8.3\text{ms}$	I_{FSM}	20	A
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

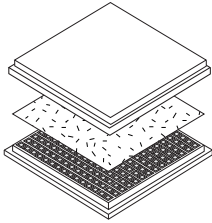
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_R	$V_R=20\text{V}$			900	μA
I_R	$V_R=30\text{V}$			1.5	mA
BV_R	$I_R=1.0\text{mA}$	40			V
V_F	$I_F=100\text{mA}$			270	mV
V_F	$I_F=500\text{mA}$			340	mV
V_F	$I_F=1.0\text{A}$			390	mV
V_F	$I_F=1.5\text{A}$			420	mV
C_J	$V_R=10\text{V}, f=1.0\text{MHz}$		50		pF

CPD85V-CMP SH1-4L

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



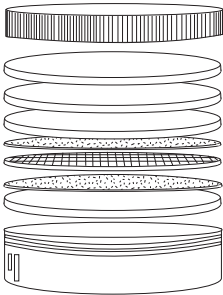
BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.

(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).

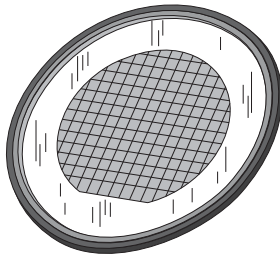
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WN)

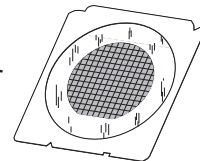


SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



R1 (10-February 2017)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

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